

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Canceled)

2. (Currently Amended) A polyamide resin composition which comprises 30 to 80% by mass of a polyamide resin (A) comprising (i) a dicarboxylic acid component unit (a-1) consisting of 30 to 100 mol% of a dicarboxylic acid component unit derived from terephthalic acid, 0 to 70 mol% of an aromatic dicarboxylic acid component unit other than the terephthalic acid, and/or 0 to 70 mol% of an aliphatic dicarboxylic acid component unit having 4 to 20 carbon atoms (provided that the total amount of these dicarboxylic acid component units is 100 mol%) and (ii) 100 mol% of a diamine component unit (a-2) consisting of a straight chain aliphatic diamine component unit having 4 to 20 carbon atoms and/or a branched chain aliphatic diamine component unit having 4 to 20 carbon atoms, as a diamine component unit; 10 to 60% by mass of an inorganic filler (B); and 5 to 50% by mass of a white pigment (C), wherein the polyamide resin composition further comprises an ultraviolet absorber (D) and a hindered amine compound (E), both the ultraviolet absorber (D) and the hindered amine compound (E) having a heating mass reduction ratio of 50% by mass or less when held at 340°C for 10 minutes under a nitrogen atmosphere, wherein the ultraviolet absorber (D) is one or more compounds selected from a benzotriazole compound, a triazine compound or a benzophenone compound.

3. (Canceled)

4. (Previously Presented) The polyamide resin composition according to claim 2, wherein the polyamide resin (A) has an intrinsic viscosity $[\eta]$ of 0.5 to 0.9 dl/g and a melting point of 260 to 350°C.

5. (Previously Presented) The polyamide resin composition according to claim 2, wherein the diamine component unit (a-2) of the polyamide resin (A) comprises one or more kinds selected from 1,6-diaminohexane, 1,10-diaminodecane, 1,11-diaminoundecane and 1,12-diaminododecane.

6. (Previously Presented) The polyamide resin composition according to claim 2, wherein the inorganic filler (B) is glass fiber.

7. (Previously Presented) The polyamide resin composition according to claim 2, wherein the white pigment (C) is titanium oxide.

8. (Previously Presented) A reflector plate which is formed from the polyamide resin composition according to claim 2.

9. (Previously Presented) A reflector plate for a light emitting diode device, which is formed from the polyamide resin composition according to claim 2.

10. (Original) The reflector plate for a light emitting diode according to claim 9, wherein reflectance retention is 80% or more.

11. (New) The polyamide resin composition according to claim 2, wherein the hindered amine compound (E) is N,N',N'',N'''-tetrakis-(4,6-bis-(butyl-(N-methyl-2,2,6,6-tetramethylpiperidin-4-yl)amino)-triazin-2-yl)-4,7-diazadecane-1,10-diamine or poly[{6-((1,1,3,3-tetramethylbutyl)amino)-1,3,5-triazine-2,4-diyl}{(2,2,6,6-tetramethyl-4-piperidyl)imino}hexamethylene{(2,2,6,6-tetramethyl-4-piperidyl)imino}].